

RoHS **Compliant**



Description

MLCC consists of a conducting material and electrodes. To manufacture a chip-type SMT and achieve miniaturization, high density and high efficiency, ceramic condensers are used. MCTT series MLCC is used in product having thickness concerned generally have high capacitance and thinner product thickness. The high dielectric constant material X7R, X5R and Y5V are used for this series product.

Features

- Standard size with thin thickness.
- Small size with high capacitance.
- Capacitor with lead-free termination (pure Tin).

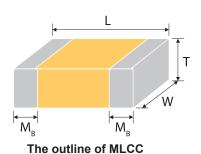
Applications

- · For LCD panels.
- For PCMCA cards.
- For IC packaging and modules.
- Any thickness concerned products.

How To Order

MCTT	31	X	225	K	100	С	Т
<u>Series</u>	<u>Size</u>	<u>Dielectric</u>	<u>Capacitance</u>	<u>Tolerance</u>	Rated Voltage	<u>Termination</u>	Packaging style
	15=0402 (1005) 18=0603 (1608) 21=0805 (2012) 31=1206 (3216) 32=1210 (3225)	B=X7R X=X5R F=Y5V	Two significant digits followed by no. of zeros. And R is in place of decimal point. Eg.: 475 = 47×10 ⁵ =4,700,000pF =4.7µF	K=±10% M=±20% Z=-20/+80%	Two significant digits followed by no. of zeros. And R is in place of decimal point. 6R3=6.3V DC 100=10V DC 160=16V DC 250=25V DC 500=50V DC	C=Cu/Ni/Sn	T=7" reeled G=13" reeled

External Dimensions



Size Inch (mm)	L (mm)	W (mm)	T max (mm)/Symbol		M _B (mm)
0402 (1005)	1 ±0.2	0.5 ±0.2	0.3 ±0.03	L	0.25 ±0.1
0603 (1608)	1.6+0.15/-0.1	0.8+0.15/-0.1	0.5 ±0.1	Н	0.4 ±0.15
0805 (2012)	2 ±0.2	1.25 ±0.2	0.85 ±0.1	Т	0.5 ±0.2
1206 (2216)	3.2 ±0.2	1.6 ±0.2	0.85 ±0.1	Т	0.6 ±0.2
1206 (3216)	3.2 ±0.2	1.0 ±0.2	1.15 ±0.15	J	0.6 ±0.2
1210 (3225)	3.2 ±0.3	2.5 ±0.2	0.85 ±0.1	Т	0.75 ±0.25
1210 (3223)	3.2 ±0.3	2.0 ±0.2	2 ±0.2	K	0.75 ±0.25

[#] Reflow soldering process only is recommended





General Electrical Data

Dielectric	X7R	X5R	Y5V					
Size	0402, 0603, 0805, 1206, 1210							
Capacitance range*	1μF to 10μF	0.22μF to 22μF	1μF to 10μF					
Capacitance tolerance**	K (±10%	Z (-20/+80%)						
Rated voltage (WVDC)	10V, 16V, 25V, 50V, 100V	6.3V, 10V, 16V, 25V	10V, 16V, 25V, 50V					
Operating temperature	-55 to +125°C	-55 to +85°C	-25 to +85°C					
Capacitance characteristic	±	+30/-80%						
Termination	Ni/Sn (lead-free termination)							

^{*} Measured at 1 ±0.2Vrms, 1kHz±10%, 30~70% related humidity, 25°C ambient temperature for X7R, X5R and at 20°C for Y5V.

Capacitance Range

X7R dielectric

	Dielectric		X7R										
	Size	0805					1206				1210		
R	Rated voltage (V DC)		16	25	50	10	16	25	50	10	16	100	
	1µF (105)							Т					
	1.5µF (155)												
<u>8</u>	2.2µF (225)		Т	Т					Т			K	
Capacitance	3.3µF (335)												
pac	4.7µF (475)	Т						Т					
ပ္မ	6.8µF (685)												
	10μF (106)	·				Т							
	22µF (226)												

X5R dielectric

	Dielectric									X5R								
	Size 0402 0603 0805			1206					1210									
R	ated voltage (V DC)	6.3	10	25	10	16	6.3	10	16	25	6.3	10	16	25	50	10	16	25
	0.22µF (224)			L	Н	Н												
<u>8</u>	0.47µF (474)	L		L														
Capacitance	1µF (105)	L			Н	Н		Т	Т	Т		Т	Т	Т				
bac	1.5µF (155)							Т	Т			Т	Т	Т				
ပ္မ	2.2µF (225)	L					Т	Т	Т	Т		Т	Т	Т	Т			
	3.3µF (335)											Т	Т	Т		Т		



^{**} Preconditioning for Class II MLCC: Perform a heat treatment at 150±10°C for 1 hour, then leave in ambient condition for 24±2 hours before measurement.



	Dielectric									X5R								
Size		0402 0		0603 0805			1206					1210						
Rated voltage (V DC)		6.3	10	25	10	16	6.3	10	16	25	6.3	10	16	25	50	10	16	25
(1)	4.7µF (475)	L			Н		Т	Т	Т	Т		Т	Т	Т		Т		
ance	6.8µF (685)																	
acita	10μF (106)						Т	Т	Т		J	J/T		Т		Т		Т
Capacitance	22uF (226)						Т	Т			Т		Т				Т	
	47uF (476)										Т							

Y5V dielectric

	Dielectric		Y5V								
	Size	0805 1206						1210			
R	ated voltage (V DC)	10	16	25	50	10	16	25	50	10	16
	1μF (105)				Т						
	1.5µF (155)										
e e	2.2µF (225)		Т			Т	Т	Т	Т		
Capacitance	3.3µF (335)	Т									
pac	4.7µF (475)	Т	Т			Т	Т				
Sa	6.8µF (685)					Т					
	10μF (106)	Т				Т				Т	
	22µF (226)										

Packaging Dimension And Quantity

Size	Thickness May	r /mm)/Crembol	7" reel			
Size	i mickness wax	(mm)/Symbol	Paper tape	Plastic tape		
0402 (1005)	0.33	L	15k	-		
0603 (1608)	0.6	Н	4k	-		
0805 (2012)	0.95	Т	4k	-		
4200 (2240)	0.95	Т	4k	-		
1206 (3216)	1.3	J	-	3k		
1210 (2225)	0.95	Т	-	3k		
1210 (3225)	2	К	-	1k		

Unit: pieces





Low Profile Multilayer SMD Ceramic Capacitor 0402 to 1210 Sizes, X7R, X5R & Y5V Dielectrics (MCTT Series)



Reliability Test Conditions and Requirements

No	Item	Test C	ondition			Requiremen	its		
1	Visual and Mechanical	-			rkable defectors to conFo		al specification sheet.		
2	Capacitance			Shall no	t exceed the	limits given in t	the detailed spec.		
				X7R/X5F	₹:				
				Rated vo	ol.	D.F.			
				100V		5%			
		Cap≤10µF, 1.0±0.2	!Vrms, 1kHz±10% !Vrms, 120Hz±20%**	50V, 25V, 16V, 10V		≤10%			
	Q/ D.F.	** Test condition: 0		6.3V		≤15%			
3	(Dissipation Factor)	1KHz±10%		Y5V:					
	i actor)	TT18X≧475(10V)	, TT15X series	Rated vo	ol.	D.F.			
				50V		≤7%			
				25V		≤9%			
				16V/10V	1	≤12.5%			
4	Dielectric Strength	To apply voltage: 2 Duration: 1 to 5 sec Charge and discha 50mA.		No evidence of damage or flash over during test.					
5	Insulation Resistance	To apply rated volta	age for max. 120sec.	≥10GΩ (or RxC≥100Ω	2-F whichever i	s smaller.		
		With no electrical lot T.C. Operating NP0 55~125°C X7R 55~125°C Y5V 25~85°C a Before initial measionly): To apply de-aging a set for 24± 2 hrs at	T.C. X7R X5R Y5V	Capacitance Within ±15° Within ±15° Within ±30°	% %				
		01005	0201						
	T	Cap0.01µF: 0.5V	Cap<0.1µF:1V						
6	Temperature Coefficient	Cap>0.01µF: 0.2V	0.1µF*Cap<1µF: 0.2V						
	Cocincion		Cap1µF: 0.1V *0201X104/16V: 0.5V						
		0402	0603						
		Cap<1µF: 1V	Cap1µF: 1V						
		Cap=1µF: 0.5V	1μF <cap4.7μf: 0.5v<="" td=""><td></td><td></td><td></td><td></td></cap4.7μf:>						
		1μF <cap<10μf: 0.2v<="" td=""><td>Cap>4.7μF: 0.2V</td><td></td><td></td><td></td><td></td></cap<10μf:>	Cap>4.7μF: 0.2V						
		Cap10µF: 0.1V							
		0805	1206/1210						
		Cap<10µF: 1V	Cap10μF: 1V						
		Cap=10µF: 0.5V	10μF <cap100μf: 0.5v<="" td=""><td></td><td></td><td></td><td></td></cap100μf:>						
		Cap>10µF: 0.2V	Cap>100µF: 0.2V						



Low Profile Multilayer SMD Ceramic Capacitor 0402 to 1210 Sizes, X7R, X5R & Y5V Dielectrics (MCTT Series)



No	Item	Test Condition	Requirements
7.	Adhesive Strength of Termination	Pressurizing force: 5N (≤0603) and 10N (>0603) Test time: 10±1 sec.	No remarkable damage or removal of the terminations.
8	Vibration Resistance	Vibration frequency: 10~55 Hz/min. Total amplitude: 1.5mm Test time: 6 hrs. (Two hrs each in three mutually perpendicular directions.) Before initial measurement (Class II only): To apply de-aging at 150°C for 1hr then set for 24± 2 hrs at room temp. Cap./DF(Q) Measurement to be made after de-aging at 150°C for 1hr then set for 24±2 hrs at room temp	No remarkable damage. Cap change and Q/D.F.: To meet initial spec.
9	Solderability	Solder temperature: 235±5°C Dipping time: 2±0.5 sec.	95% min. coverage of all metalized area
10	Bending Test	The middle part of substrate shall be pressurized by means of the pressurizing rod at a rate of about 1mm per second until the deflection becomes: 5mm and then the pressure shall be maintained for 5±1 sec. Measurement to be made after keeping at room temp. for 24±2 hrs.	No remarkable damage. Cap change: X7R/X5R: within ±12.5% Y5V: within ±30% (This capacitance change means the change of capacitance under specified flexure of substrate from the capacitance measured before the test.)
11	Resistance to Soldering Heat	Solder temperature: 260±5°C Dipping time: 10±1 sec Preheating: 120 to 150°C for 1 minute before immerse the capacitor in a eutectic solder. Before initial measurement (Class II only): Perform 150+0/-10°C for 1 hr and then set for 24±2 hrs at room temp. Measurement to be made after keeping at room temp. for 24±2 hrs.	No remarkable damage. Cap change: X7R/X5R: within ±7.5% Y5V: within ±20% Q/D.F., I.R. and dielectric strength: To meet initial requirements. 25% max. leaching on each edge.
12	Temperature Cycle	Conduct the five cycles according to the temperatures and time. Step Temp. (°C) Time (min.)	No remarkable damage. Cap change: X7R/X5R: within ±7.5% Y5V: within ±20% Q/D.F., I.R. and dielectric strength: To meet initial requirements.



Low Profile Multilayer SMD Ceramic Capacitor 0402 to 1210 Sizes, X7R, X5R & Y5V Dielectrics (MCTT Series)



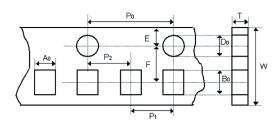
No	Item	Test Condition		Requireme	nts			
		Test temp.: 40±2°C	No remarkable damage. Cap change: X7R/X5R: within ±25%					
		Humidity: 90~95% RH	Rated vol.	D.F.				
		Test time: 500+24/-0hrs.	100V	≤7.5%				
	- \ - /	Before initial measurement (Class II only): Perform 150+0/-10°C for 1 hr and	25V, 16V	≤15%				
13		then set for 24±2 hrs at room temp	10V	≤20%				
	Steady State	Measurement to be made after keeping	50V, 6.3V	≤30%				
		at room temp. for 24±2 hrs. Cap. / DF(Q) / I.R. Measurement to be	Y5V:					
		made after de-aging at 150°C for 1hr	Rated vol.	D.F.				
		then set for 24±2 hrs at room temp	50V	≤10%				
			25V	≤15%				
			16V, 10V	≤20%				
			I.R.: 1GΩ or RxC≧10	Ω-F whichev	er is smaller.			
		Test temp.: 40±2°C Humidity: 90~95%RH	No remarkable damage Cap change: X7R/X5I Y5V: wit Q/D.F. value: X7R/X5R:	R: within ±25	% 3V, within +30/-40%			
		Test time: 500+24/-0 hrs.	Rated vol.	D.F.				
		To apply voltage : rated voltage	100V	≤7.5%				
	Humidity	Before initial measurement (Class II only): To apply test voltage for 1hr at	25V, 16V	≤15%				
14	(Damp Heat)	40°C and then set for 24±2 hrs at room	50V, 10V	≤20%				
	Load	temp.	6.3V	≤30%				
		Measurement to be made after keeping at room temp. for 24±2 hrs.	Y5V:					
		Cap. / DF(Q) / I.R. Measurement to be	Rated vol.	D.F.				
		made after de-aging at 150°C for 1hr then set for 24±2 hrs at room temp.	50V	≤10%				
		then set for 2412 fills at room temp.	25V	≤15%				
			16V, 10V	≤20%				
			I.R.: 500MΩ or RxC≧5 Ω-F whichever is smaller.					



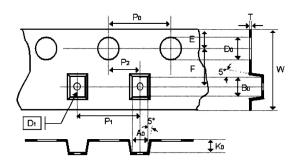
No	Item		Test Co	ndition			Requireme	nts		
		X5R, Y5V Test time:	XX7E: 125	-0 hrs.	ed	Q/D.F. value: X7R/X5R:	5R: within ±25°	% 3V, within +30/-40%		
		100% of r	ated voltag	ge for belo	w range.	Rated vol.	D.F. ≤7.5%			
	High	Size	Dielectric	Rated voltage	Capaci- tance	25V, 16V	≤1.5%			
15	Temperature	TT15	X5R	6.3V	C≧1µF	50V, 10V	≤20%			
"	Load	TT18	Y5V	6.3V,10V	C≧2.2µF	6.3V	≤30%			
	(Endurance)	TT21	Y5V	6.3V	C≧10µF	Y5V:				
		TT31 Y5V 6.3V C≧22μF			Rated vol.	D.F.]			
			tial measu apply test v	•		50V	≤10%			
			and then			25V	≤15%]		
		room tem	p.			16V, 10V	≤20%]		
		Measurement to be made after keeping at room temp. for 24±2 hrs			I.R.: $1G\Omega$ or $RxC \ge 5$ Ω -F whichever is smaller.					

Appendixes

Tape & Reel Dimensions



The dimension of paper tape



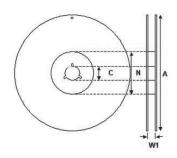
The dimension of plastic tape

Size	0402	0603	0805	1206		1210	
Thickness	L	Н	Т	Т	J	Т	K
A ₀	0.7 ±0.2	1.05 ±0.3	1.5 ±0.2	1.9 ±0.5	<2	< 3.05	1.05 ±0.3
B ₀	1.2 ±0.2	1.8 ±0.3	2.3 ±0.2	3.5 ±0.5	< 3.7	< 3.8	1.05 ±0.3
Т	≦0.8	≦1.2	≦1.2	≦1.2	0.23 ±0.1	0.23 ±0.1	≦1.2
K ₀	-	-	-	-	<2.5	<1.5	-
W	8 ±0.3	8 ±0.3	8 ±0.3	8 ±0.3	8 ±0.3	8 ±0.3	8 ±0.3
P ₀	4 ±0.1	4 ±0.1	4 ±0.1	4 ±0.1	4 ±0.1	4 ±0.1	4 ±0.1
10xP ₀	40 ±0.2	40 ±0.2	40 ±0.2	40 ±0.2	40 ±0.2	40 ±0.2	40 ±0.2
P ₁	2 ±0.1	4 ±0.1	4 ±0.1	4 ±0.1	4 ±0.1	4 ±0.1	4 ±0.1
P ₂	2 ±0.05	2 ±0.05	2 ±0.05	2 ±0.05	2 ±0.05	2 ±0.05	2 ±0.05
D ₀	1.5 +0.1/-0						





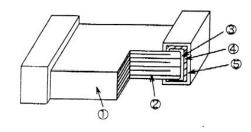
Size	0402	0603	0805	1206		1210	
Thickness	L	Н	Т	Т	J	Т	K
D ₁	-		-	-	1 ±0.1	1 ±0.1	-
Е	1.75 ±0.1	1.75 ±0.1	1.75 ±0.1	1.75 ±0.1	1.75 ±0.1	1.75 ±0.1	1.75 ±0.1
F	3.5 ±0.05	3.5 ±0.05	3.5 ±0.05	3.5 ±0.05	3.5 ±0.05	3.5 ±0.05	3.5 ±0.05



Size	0402, 0603, 0805, 1206, 1210				
Reel size	7"	10"	13″		
С	13 +0.5/-0.2	13 +0.5/-0.2	13 +0.5/-0.2		
W1	8.4 +1.5/-0	8.4+1.5/-0	8.4 +1.5/-0		
А	178 ±0.1	250 ±1	330 ±1		
N	60 +1/-0	100 ±1	100 ±1		

The dimension of reel

Constructions:



No.	Na	me	NP0*	NPO, X7R, Y5V	
1	Ceramic	material	BaTiO₃ based		
2	Inner el	ectrode	Ni		
3		Inner layer		Cu	
4	Termination	Middle layer	Ni		
5		Outer layer	Sn (Matt)		

Storage and handling conditions

- (1) To store products at 5°C to 40°C ambient temperature and 20 to 70%. related humidity conditions.
- (2) The product is recommended to be used within one year after shipment. Check solderability in case of shelf life extension is needed.

Cautions:

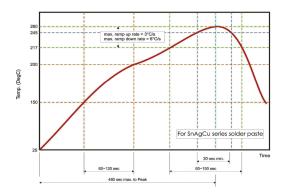
- a. The corrosive gas reacts on the terminal electrodes of capacitors, and results in the poor solderability. Do not store the capacitors in the ambience of corrosive gas (e.g., hydrogen sulfide, sulfur dioxide, chlorine, ammonia gas etc.)
- b. In corrosive atmosphere, solderability might be degraded, and silver migration might occur to cause low reliability.
- c. Due to the dewing by rapid humidity change, or the photochemical change of the terminal electrode by direct sunlight, the solderability and electrical performance may deteriorate. Do not store capacitors under direct sunlight or dewing condition. To store products on the shelf and avoid exposure to moisture.



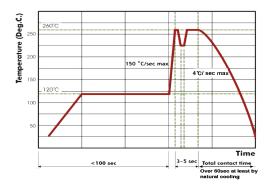


Recommended Soldering Conditions:

The lead-free termination MLCCs are not only to be used on SMT against lead-free solder paste, but also suitable against lead-containing solder paste. If the optimized solder joint is requested, increasing soldering time, temperature and concentration of N2 within oven are recommended.



Recommended reflow soldering profile for SMT process with SnAgCu series solder paste.



Recommended wave soldering profile for SMT process with SnAgCu series solder.

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